Haptic Solutions for Mobile Devices
Enhance your mobile device with advanced haptic feedback

Mobile Device Design Challenges
The mobile market is extremely competitive and constantly changing. The ability to create a differentiated product is becoming more and more difficult. Key features that once separated your smartphone or tablet from its competitors have now become industry standards. Consumers are looking for cool and new innovative products that use cutting edge technology. For this reason, mobile manufacturers need to find a way to enhance the user experience and provide the consumer with something they’ve never seen before.

Where does TI come in?
Texas Instruments offers a complete line of haptic drivers which have the ability to drive eccentric rotating mass (ERM), linear resonant actuator (LRA), and piezoelectric actuators. TI’s haptic drivers have the ability to intelligently amplify the haptic waveform to achieve the maximum voltage an actuator can operate at. This allows for maximum impact to the user. Within TI’s haptic drivers is the ability to store software that can generate the waveform as well.

By adding haptic effects, mobile manufacturers can differentiate their product by giving the user a tactile feedback rather than just an audible feedback. The tactile feedback in these mobile devices will give the user a “real feel” to typing, clicking, scrolling, and swiping, on the capacitive touch display on their smartphone or tablet. In addition, with the audio-to-haptics feature that is available in TI’s DRV2605, mobile manufacturers can create more immersive multimedia and gaming, adding even more to the user experience.

With the global mobile device market looking for a way to differentiate itself from its predecessors, adding haptics to your device will be a technology that will be a “must-have” in your next smartphone or tablet.

Visit www.ti.com/haptics for more information.
**Applications**

TI's haptic drivers are used in more than 20 different mass-production smartphones and tablets in markets across the world. A sample of the solutions used in these applications include:

- DRV8601 with ERM
- DRV2603 with LRA
- DRV2604 with LRA
- DRV2605 with ERM or LRA
- DRV2665 with piezo (high-definition haptics)

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## Haptic Drivers

<table>
<thead>
<tr>
<th>Device</th>
<th>Description</th>
<th>V_{\text{max}} (Max) (V)</th>
<th>Input Signal</th>
<th>I_{\text{typ}} (Typ) (mA)</th>
<th>Startup Time (ms)</th>
<th>Haptic Actuator Type</th>
<th>V_{\text{o}} (Max) (V)</th>
<th>V_{\text{i}} (Min) (V)</th>
<th>Operating Temp Range (ºC)</th>
<th>Package</th>
<th>Price*</th>
</tr>
</thead>
<tbody>
<tr>
<td>DRV2667</td>
<td>Piezo Haptic Driver with Boost, Digital Front End, and Internal Waveform Memory</td>
<td>200</td>
<td>FC, PWM, Analog</td>
<td>0.13</td>
<td>2</td>
<td>Piezo</td>
<td>5.5</td>
<td>3</td>
<td>−40 to 85</td>
<td>QFN-20</td>
<td>2.95</td>
</tr>
<tr>
<td>DRV2604</td>
<td>Haptic Driver for ERM/LRA with Waveform Memory and Smart Loop Architecture</td>
<td>5.5</td>
<td>FC, PWM, Analog</td>
<td>0.6</td>
<td>0.7</td>
<td>ERM, LRA</td>
<td>5.5</td>
<td>2.5</td>
<td>−40 to 85</td>
<td>9DSBGA</td>
<td>1.15</td>
</tr>
<tr>
<td>DRV2605</td>
<td>Haptic Driver for ERM/LRA with Built-In Library and Smart Loop Architecture</td>
<td>5.5</td>
<td>FC, PWM, Analog</td>
<td>—</td>
<td>0.7</td>
<td>ERM, LRA</td>
<td>5.5</td>
<td>2.5</td>
<td>−40 to 85</td>
<td>9DSBGA</td>
<td>1.60</td>
</tr>
<tr>
<td>DRV2603</td>
<td>Haptic Driver with Auto Resonance Tracking for LRA and Optimized Drive for ERM</td>
<td>—</td>
<td>PWM, Analog</td>
<td>1.5</td>
<td>1.3</td>
<td>ERM, LRA</td>
<td>5.2</td>
<td>2.5</td>
<td>−40 to 85</td>
<td>QFN-10</td>
<td>0.70</td>
</tr>
<tr>
<td>DRV2665</td>
<td>Piezo Haptic Driver with Integrated Boost Converter and Digital Front End</td>
<td>200</td>
<td>FC, PWM, Analog</td>
<td>5</td>
<td>2</td>
<td>Piezo</td>
<td>5.5</td>
<td>3</td>
<td>−40 to 70</td>
<td>QFN-20</td>
<td>2.50</td>
</tr>
<tr>
<td>DRV8662</td>
<td>Piezo Haptic Driver with Integrated Boost Converter</td>
<td>100</td>
<td>PWM, Analog</td>
<td>5</td>
<td>1.5</td>
<td>Piezo</td>
<td>5.5</td>
<td>3</td>
<td>−40 to 70</td>
<td>QFN-20</td>
<td>1.75</td>
</tr>
<tr>
<td>DRV8601</td>
<td>400 mA Fully Differential Motor Driver with 1.8-V Input Logic Thresholds</td>
<td>5.5</td>
<td>PWM, Analog</td>
<td>1.7</td>
<td>0.1</td>
<td>ERM, LRA</td>
<td>5.5</td>
<td>2.5</td>
<td>−40 to 85</td>
<td>BGA-8</td>
<td>MICROSTAR JUNIOR™, SON-8</td>
</tr>
</tbody>
</table>

*Suggested resale price in U.S. dollars in quantities of 1,000.

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Visit [www.ti.com/haptics](http://www.ti.com/haptics) for more information.

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